

Description: 2.4GHz Ceramic Chip Antenna

PART NUMBER: W3008G

Series: Ceramic Chip Antenna



Features:

- Frequency 2400-2483.5MHz
- Size 3.2 x 1.6 x 1.1mm
- Efficiency >80%
- Gain >1.5dBi
- SMD compatible
- MSL 1

Applications:

- 2.4GHz ISM band radios
- · Bluetooth, BLE
- WiFi 2.4GHz
- IoT, M2M devices

All dimensions are in mm / inches

Issue: 1946

In the effort to improve our products, we reserve the right to make changes judged to be necessary. CONFIDENTIAL AND PROPRIETARY INFORMATION

This document contains confidential and proprietary information of Pulse Electronics, Inc. (Pulse) and is protected by copyright, trade secret and other state and federal laws. Its receipt or possession does not convey any rights to reproduce, disclose its contents, or to manufacture, use or sell anything it may describe. Reproduction, disclosure or use without specific written authorization of Pulse is strictly forbidden. For more information:

Pulse Worldwide Headquarters 15255 Innovation Drive #100 San Diego, CA 92128 USA Tel:1-858-674-8100 Pulse/Larsen Antennas 18110 SE 34th St Bldg 2 Suite 250 Vancouver, WA 98683 USA Tel: 1-360-944-7551 Europe Headquarters Pulse GmbH & Do, KG Zeppelinstrasse 15 Herrenberg, Germany Tel: 49 7032 7806 0 Pulse (Suzhou) Wireless Products Co, Inc. 99 Huo Ju Road(#29 Bldg,4th Phase Suzhou New District Jiangsu Province, Suzhou 215009 PR China Tel: 86 512 6807 9998



Description: 2.4GHz Ceramic Chip Antenna

Series: Ceramic Chip Antenna

PART NUMBER: W3008G

ELECTRICAL SPECIFICATIONS

Antenna Type	Ceramic Chip
Frequency	2400-2483.5MHz
Nominal Impedance	50 Ω
VSWR	<1.6:1
Radiation Pattern	Omni
Gain	>1.5dBi
Efficiency	>80%
Polarization	Linear
Power Withstanding	2W

MECHANICAL SPECIFICATIONS

Weight	0.03 g
Overall Length	3.2 [0.126] MM [INCHES]
Over all width	1.6 [0.063] MM [INCHES]
Over all thickness	1.1 [0.043] MM [INCHES]
MSL (Moisture Sensitivity Level)	1

ENVIRONMENTAL SPECIFICATIONS

Operating Temperature	-40 / +85 ° C
Storage Temperature	-40 / +85 ° C
RoHS Compliant	Yes

2

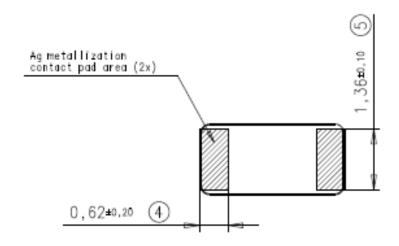


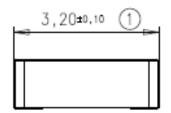
Description: 2.4GHz Ceramic Chip Antenna

Series: Ceramic Chip Antenna

PART NUMBER: W3008G

MECHANICAL DRAWING





Antenna features		
No.	Terminal Name	Terminal Dimensions
1	Feed / GND	0.62 x 1.36 mm
2	Feed / GND	0.62 x 1.36 mm
Antenna is symmetrical. Either of terminals 1 or 2 can be Feed / GND		

Note: This type of antenna is called loaded PIFA. One pad (on the bottom of the ceramic chip antenna) that feedline and GND are connected is a basic PIFA antenna structure. And, another pad on the other side that only GND is connected is for capacitive loading. Loaded capacitive value is optimized by the gap distance between two pads on the top surface. In PIFA, there is short mechanism usually in proximity to feed. This RF shorting affects impedance and current distribution mechanism of antenna. The actual antenna top face can seem to be mirrored, however it can be used same as the non-mirrored version. Please follow the design recommendation specified in this data sheet for either case.





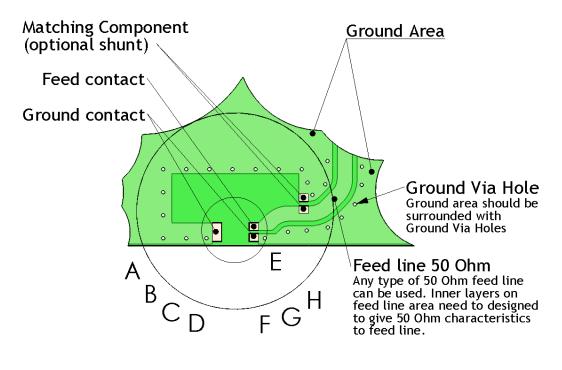
Series: Ceramic Chip Antenna

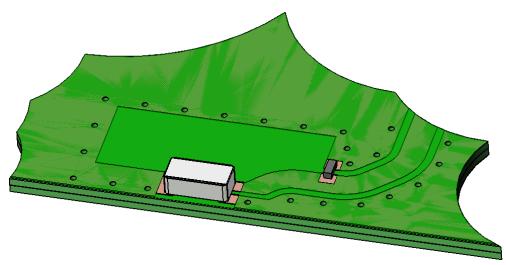
PART NUMBER: W3008G

OTHER SPECIFICATIONS

PWB Layout

Typical performance (test board size 80x37 mm, PWB ground clearance area 11.00 x 6.25 mm) Antenna placed 80mm edge center position.











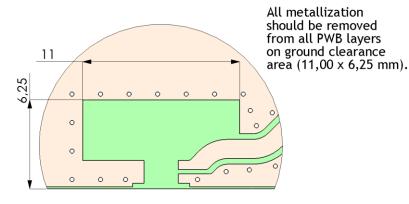
Series: Ceramic Chip Antenna

PART NUMBER: W3008G

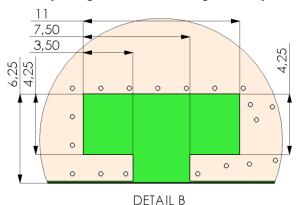
OTHER SPECIFICATIONS

Ground cleared under antenna, clearance area 11.00 x 6.25 mm

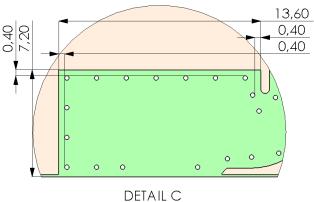
Ground clearance area (11,00 x 6,25 mm)



DETAIL A Opening in bottom/inner ground layers



Opening in other layers (no ground/ RF)









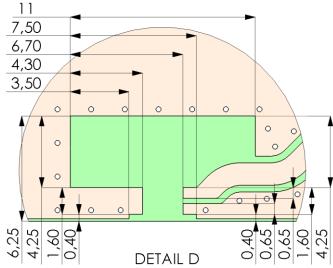
Series: Ceramic Chip Antenna

PART NUMBER: W3008G

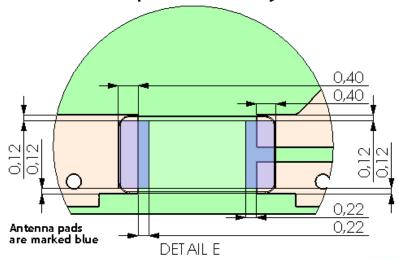
OTHER SPECIFICATIONS

PWB pad dimensions and antenna position

Pad dimensions in top copper



Antenna position on PWB layout





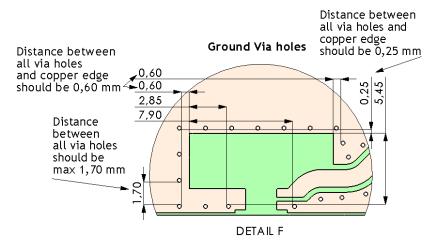


Series: Ceramic Chip Antenna

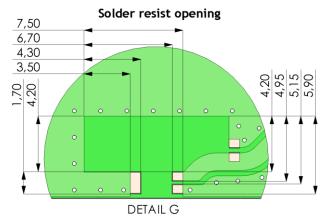
PART NUMBER: W3008G

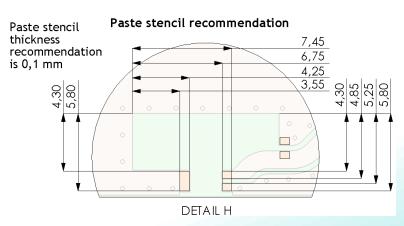
OTHER SPECIFICATIONS

Typical Ground via hole placement in PWB layout



Solder resist opening and paste stencil recommendations







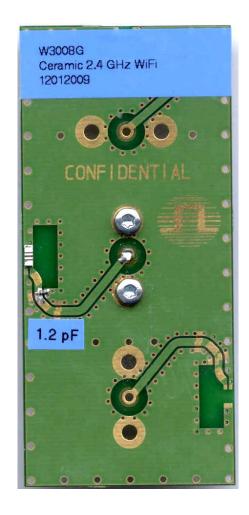
Description: 2.4GHz Ceramic Chip Antenna

Series: Ceramic Chip Antenna

PART NUMBER: W3008G

TEST SETUP

All RF parameters measured on 37x80mm evaluation board. Antenna placement on side center position of PCB long edge. Shunt 1.2pF capacitor for matching.





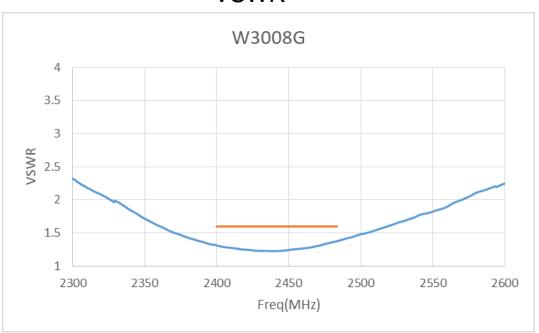
Description: 2.4GHz Ceramic Chip Antenna

Series: Ceramic Chip Antenna

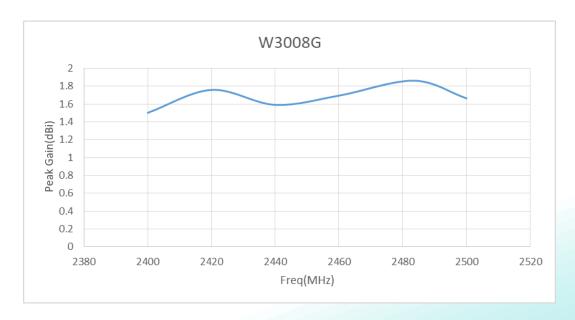
PART NUMBER: W3008G

CHARTS

VSWR



Peak Gain





Description: 2.4GHz Ceramic Chip Antenna

Series: Ceramic Chip Antenna

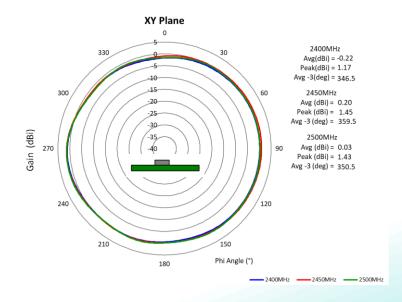
PART NUMBER: W3008G

CHARTS

Radiation Efficiency



Radiation pattern X-Y plane





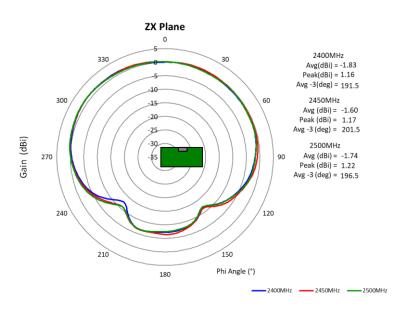


Series: Ceramic Chip Antenna

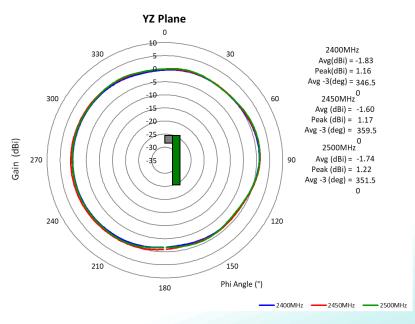
PART NUMBER: W3008G

CHARTS

Radiation pattern Z-X plane



Radiation pattern Y-Z plane



Issue: 1946

ROHS





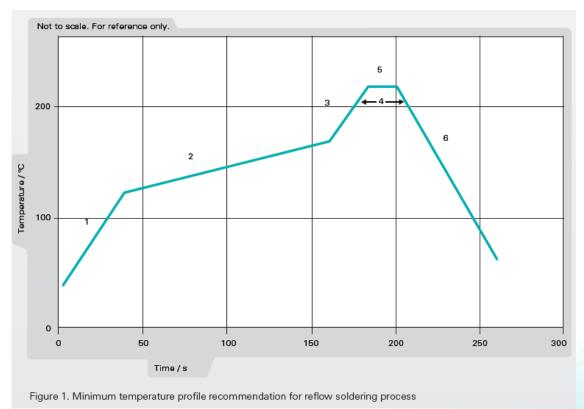
Series: Ceramic Chip Antenna

PART NUMBER: W3008G

Recommendation for reflow soldering process

Printing stencil thickness 0,15 - 0,25 mm is recommended for the solder paste. The maximum soldering temperature should not exceed 260°C. The temperature profile recommendations for reflow soldering process is presented in the Figures 1 and 2. The reflow profile presented in figure 1 describes minimum reflow temperatures. The reflow profile presented in figure 2 describes maximum reflow temperatures. located at the center of the coverage area.

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5 °C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3 °C/s
4	Time above 217 °C	Max 30 sec
5	Peak temperature in reflow	230 °C for 10 seconds
6	Temperature gradient in cooling	Max -5 °C/s









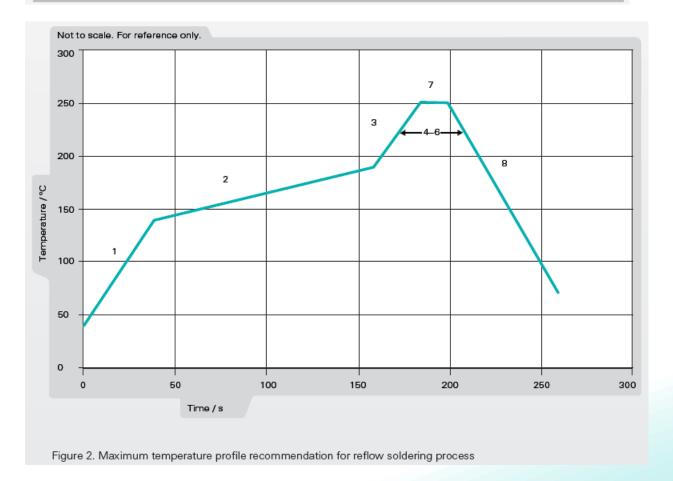
Description: 2.4GHz Ceramic Chip Antenna

Series: Ceramic Chip Antenna

PART NUMBER: W3008G

Recommendation for reflow soldering process

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5 °C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3 °C/s
4	Time above 217 °C	Max 60 sec
5	Time above 230 °C	Max 50 sec
6	Time above 250 °C	Max 10 sec
7	Peak temperature in reflow	260 °C for 5 seconds
8	Temperature gradient in cooling	Max -5 °C/s







Description: 2.4GHz Ceramic Chip Antenna

Series: Ceramic Chip Antenna

PART NUMBER: W3008G

PACKAGING-1

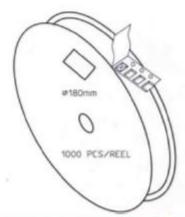
3000pcs antennas per 7" reel

5pcs 7" reel per inner package box

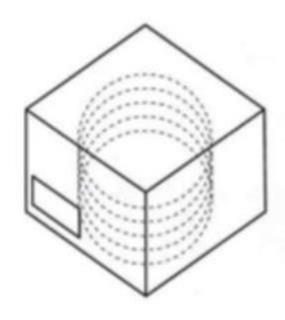
2pcs inner box per out box

Total 30000pcs antenna per out box

Out box size: 390mmx215mmx165mm







LEVEL

NOT MOISTURE SENSITIVE



These Devices do not require special storage conditions provided:

- They are maintained at conditions equal to or less than 30°C and 85% RH.
- They are solder reflowed at a peak body temperture which does not exceed 260°C.

Note: Level and body temperture defined by IPC/JEDEC J-STD-020

Issue: 1946

ROHS

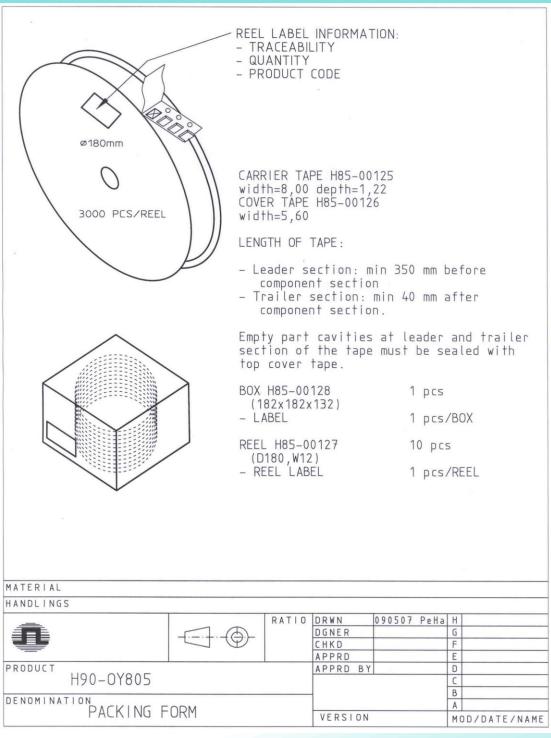


Description: 2.4GHz Ceramic Chip Antenna

Series: Ceramic Chip Antenna

PART NUMBER: W3008G

PACKAGING-2



X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Antennas category:

Click to view products by Pulse manufacturer:

Other Similar products are found below:

GAN30084EU 930-033-R GW17.07.0250E 1513563-1 EXE902SM APAMPG-117 MAF94383 W3908B0100 W6102B0100 YE572113-30RSMM 108-00014-50 66089-2406 SPDA17RP918 A09-F8NF-M A09-F5NF-M RGFRA1903041A1T W3593B0100 W3921B0100 SIMNA-868 SIMNA-915 SIMNA-433 W1044 W1049B090 A75-001 WTL2449CQ1-FRSMM CPL9C EXB148BN 0600-00060 TRA9020S3PBN-001 Y4503 GD5W-28P-NF MA9-7N GD53-25 GD5W-21P-NF C37 MAF94051 MA9-5N EXD420PL B1322NR QWFTB120 MAF94271 MAF94300 GPSMB301 FG4403 AO-AGSM-OM54 5200232 MIKROE-2349 WCM.01.0111 MIKROE-2393 MIKROE-2352